



TotalEnergies

Refining & Chemicals
Polymers

Polyethylene HDPE 55200

Provisional Technical data sheet
High Density Polyethylene BLOW MOULDING
Produced in Europe

Description

HDPE 55200 is a high density polyethylene (HDPE) with very good balance of stiffness and high Environmental Stress Crack Resistance (ESCR). It has been specifically designed for the manufacture of blow moulded packaging for aggressive household, industrial and cosmetics liquids. Thanks to its high resistance to ESCR, it is ideal for boosting the properties of PCR-PE.

HDPE 55200 is a pellet grade and contains antioxidants.

Characteristics

Property	Method	Unit	Typical value (*)
Density	ISO 1183	g/cm ³	0.955
Melt Flow Rate (190°C/2.16 kg)	ISO 1133/D	g/10 min	0.25
Melt Flow Rate (190°C/21.6 kg)	ISO 1133/G	g/10 min	20
ESCR AntaroX 100%	ASTM D 1693B	h	F ₅₀ = 120
Notched Charpy Impact Resistance 23°C	ISO 179-1	kJ/m ²	15

(*) Data not intended for specification purposes

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

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